

54LS20,DM54LS20,DM74LS20

54LS20 DM54LS20 DM74LS20 Dual 4-Input NAND Gates



Literature Number: SNOS291A

54LS20/DM54LS20/DM74LS20 Dual 4-Input NAND Gates

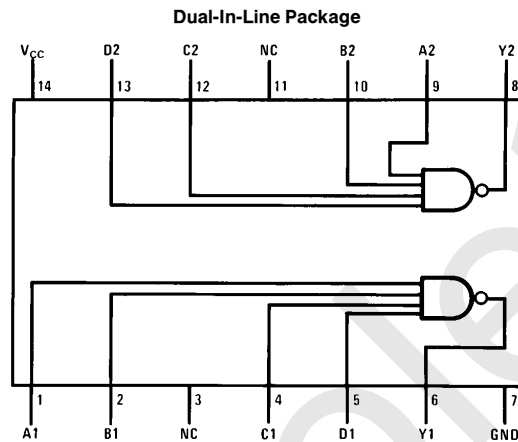
General Description

This device contains two independent gates each of which performs the logic NAND function.

Features

- Alternate Military/Aerospace device (54LS20) is available. Contact a National Semiconductor Sales Office/Distributor for specifications

Connection Diagram



TL/F/6355-1

Order Number 54LS20DMQB, 54LS20FMQB, 54LS20LMQB,
DM54LS20J, DM54LS20W, DM74LS20M or DM74LS20N
See NS Package Number E20A, J14A, M14A, N14A or W14B

Function Table

$$Y = \overline{ABCD}$$

Inputs				Output
A	B	C	D	Y
X	X	X	L	H
X	X	L	X	H
X	L	X	X	H
L	X	X	X	H
H	H	H	H	L

H = High Logic Level

L = Low Logic Level

X = Either Low or High Logic Level

Absolute Maximum Ratings (Note)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	
DM54LS and 54LS	−55°C to +125°C
DM74LS	0°C to +70°C
Storage Temperature Range	−65°C to +150°C

Note: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the "Electrical Characteristics" table are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Recommended Operating Conditions

Symbol	Parameter	DM54LS20			DM74LS20			Units
		Min	Nom	Max	Min	Nom	Max	
V _{CC}	Supply Voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High Level Input Voltage	2			2			V
V _{IL}	Low Level Input Voltage			0.7			0.8	V
I _{OH}	High Level Output Current			−0.4			−0.4	mA
I _{OL}	Low Level Output Current			4			8	mA
T _A	Free Air Operating Temperature	−55		125	0		70	°C

Electrical Characteristics over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 1)	Max	Units
V _I	Input Clamp Voltage	V _{CC} = Min, I _I = −18 mA			−1.5	V
V _{OH}	High Level Output Voltage	V _{CC} = Min, I _{OH} = Max, V _{IL} = Max	DM54 2.5	3.4		V
			DM74 2.7	3.4		
V _{OL}	Low Level Output Voltage	V _{CC} = Min, I _{OL} = Max, V _{IH} = Min	DM54 0.25	0.25	0.4	V
		I _{OL} = 4 mA, V _{CC} = Min	DM74 0.25	0.35	0.5	
I _I	Input Current @ Max Input Voltage	V _{CC} = Max, V _I = 7V			0.1	mA
I _{IH}	High Level Input Current	V _{CC} = Max, V _I = 2.7V			20	μA
I _{IL}	Low Level Input Current	V _{CC} = Max, V _I = 0.4V			−0.36	mA
I _{OS}	Short Circuit Output Current	V _{CC} = Max (Note 2)	DM54 −20		−100	mA
			DM74 −20		−100	
I _{CCH}	Supply Current with Outputs High	V _{CC} = Max		0.4	0.8	mA
I _{CCL}	Supply Current with Outputs Low	V _{CC} = Max		1.2	2.2	mA

Switching Characteristics at V_{CC} = 5V and T_A = 25°C (See Section 1 for Test Waveforms and Output Load)

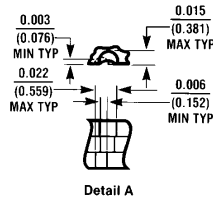
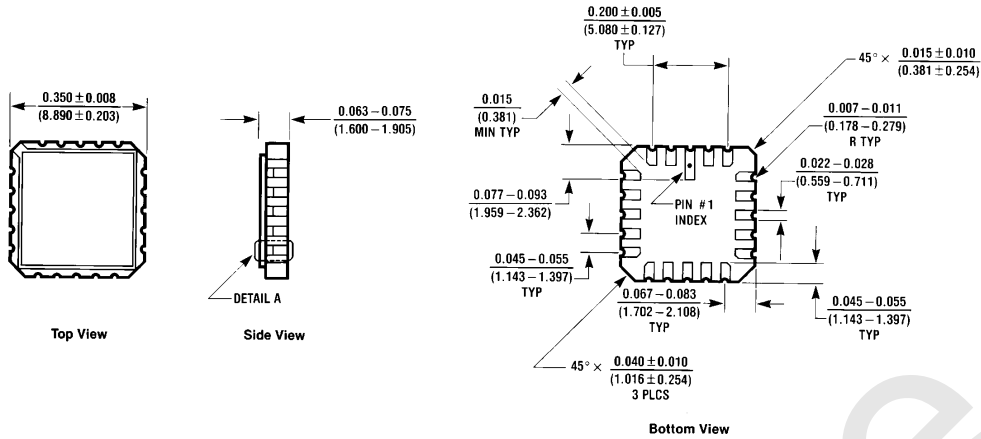
Symbol	Parameter	R _L = 2 kΩ				Units
		C _L = 15 pF		C _L = 50 pF		
		Min	Max	Min	Max	
t _{PLH}	Propagation Delay Time Low to High Level Output	3	10	4	15	ns
t _{PHL}	Propagation Delay Time High to Low Level Output	3	10	4	15	ns

Note 1: All typicals are at V_{CC} = 5V, T_A = 25°C.

Note 2: Not more than one output should be shorted at a time, and the duration should not exceed one second.

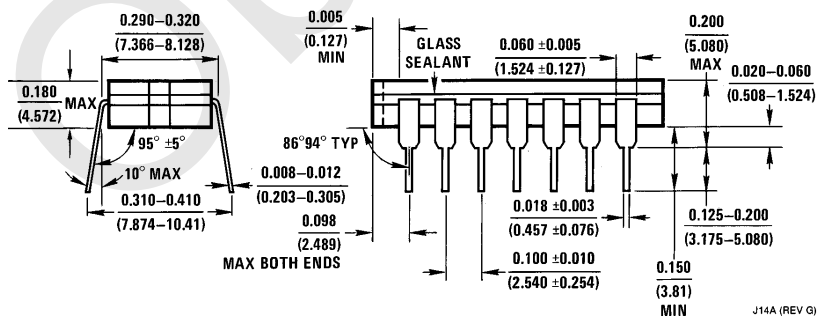
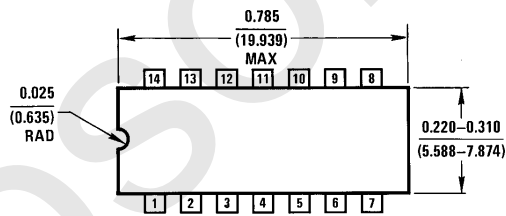
Obsolete

Physical Dimensions inches (millimeters)



Ceramic Leadless Chip Carrier Package (E)
 Order Number 54LS20LMQB
 NS Package Number E20A

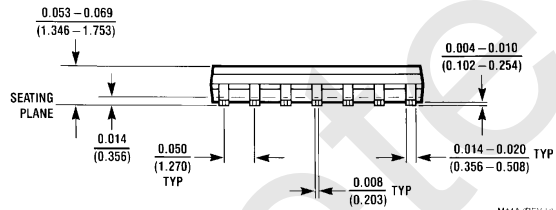
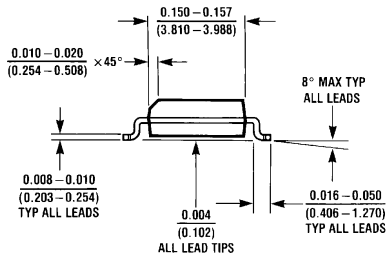
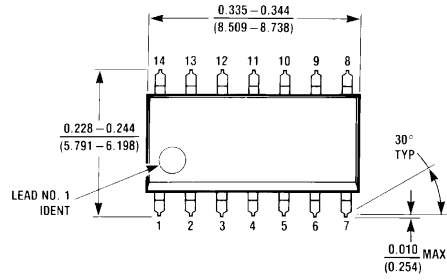
E20A (REV D)



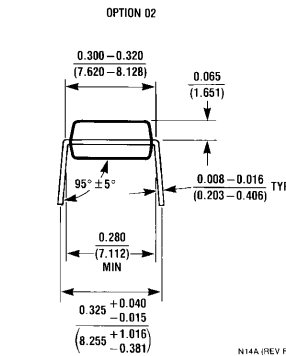
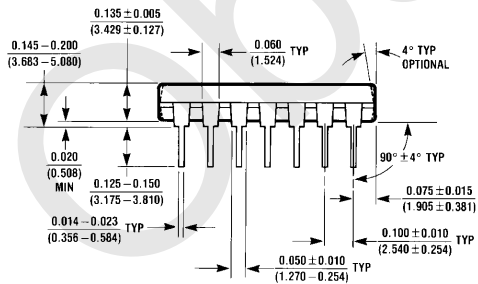
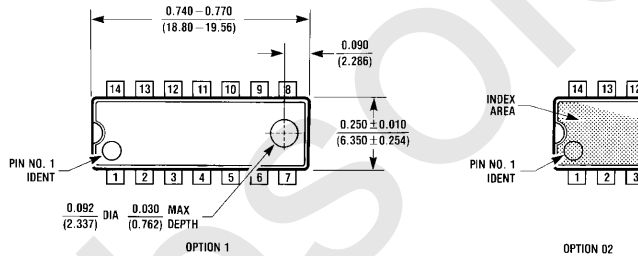
14-Lead Ceramic Dual-In-Line Package (J)
 Order Number 54LS20DMQB or DM54LS20J
 NS Package Number J14A

J14A (REV G)

Physical Dimensions inches (millimeters) (Continued)

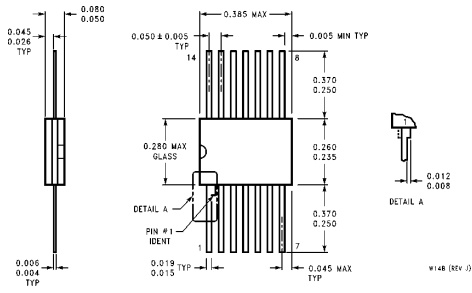


14-Lead Small Outline Molded Package (M)
Order Number DM74LS20M
NS Package Number M14A



14-Lead Molded Dual-In-Line Package (N)
Order Number DM74LS20N
NS Package Number N14A

Physical Dimensions inches (millimeters) (Continued)



14-Lead Ceramic Flat Package (W)
Order Number 54LS20FMQB or DM54LS20W
NS Package Number W14B

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National Semiconductor Corporation
 1111 West Bardin Road
 Arlington, TX 76017
 Tel: 1(800) 272-9959
 Fax: 1(800) 737-7018

National Semiconductor Europe
 Fax: (+49) 0-180-530 85 86
 Email: cnjwge@tevm2.nsc.com
 Deutsch Tel: (+49) 0-180-530 85 85
 English Tel: (+49) 0-180-532 78 32
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National Semiconductor Hong Kong Ltd.
 19th Floor, Straight Block,
 Ocean Centre, 5 Canton Rd.
 Tsimshatsui, Kowloon
 Hong Kong
 Tel: (852) 2737-1600
 Fax: (852) 2736-9960

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